BRIGHTEK (EUROPE) LIMITED Brighten Up The World With CED!

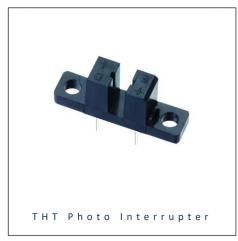


PRODUCT DATASHEET



- THT Through hole
- ▶ 24.5x6.3x10.8mm
- Photo Interrupter (PI)





N0P08L51

APPLICATIONS:

- Voltage Detector
- Monitor Sensor

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THT Photo Interrupter



FEATURES:

- Package: THT 4-Pins Photo Interrupter Block
- Viewing Angle: 40°
- Infrared Peak Wavelength: 940nm
- Wavelength of Maxi. Sensitivity: 940nm
- Materials:

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- Die: GaAlAs-GaAs (IR) / Silicon (PT)
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- Soldering methods: Hand; Soldering Heat (DIP)
- MSL Level: 3 acc. to JEDEC
- Packing: Bulk in Carton



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

	Parameter	Symbol	Ratings	Unit
IR	Power Dissipation	PD	75	mW
	Continuous Forward Current	lf	50	mA
	Peak Forward Current (pulse width: 10μs, duty cycle 1%)	Ipf	1	А
	Reverse Voltage	V _R	5	V
	Operating Temperature	Topr	-40~+85	°C
	Storage Temperature	Тѕтб	-40~+100	°C
PT	Power Dissipation	PD	75	mW
	Emitter-Collector Breakdown Voltage	BV _{ECO}	5	V
	Collector-Emitter Sustaining Voltage	Vce	30	V
	Relative Humidity at 85°C	H _R	85	%
	Operating Temperature	Topr	-40~+85	°C
	Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

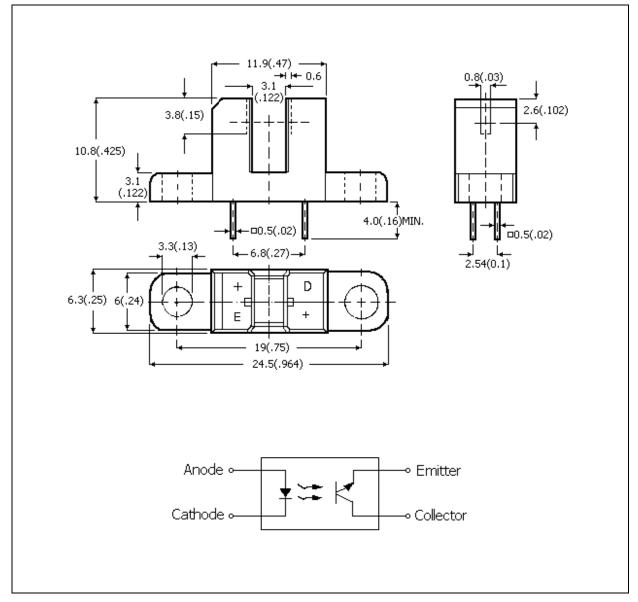
Parameter		Symbol	Values			Unit	Test
			Min.	Тур.	Max.	Unit	Condition
Input	Forward Voltage	VF		1.2	1.5	V	I⊧=20mA V _R =4V
	Reverse Leakage Current	I _R			10	μA	
Output	Dark Current	ld			100	nA	V_{CE} =10V E _e =0mW/cm ²
	Junction Capacitance	СТ				pF	
Coupled	Output Current	lc	0.5			mA	I _F =20mA V _{CE} =5V I _C =2mA RL=1KΩ
	Rise Time	Tr		5		μS	
	Fall Time	Tf		5		μS	

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OUTLINE DIMENSION:

Package Dimension:



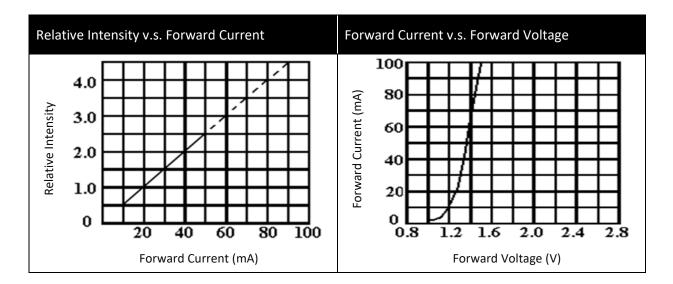
1. All dimensions are in millimetre (mm).

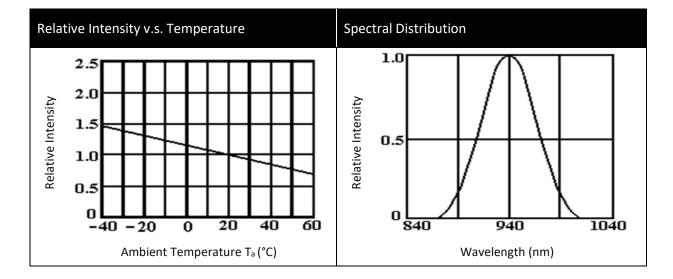
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2. Tolerance ± 0.2 mm, unless otherwise noted.



ELECTRO-OPTICAL CHARACTERISTICS (IR):

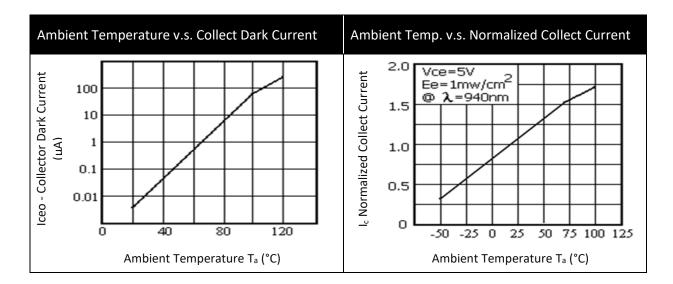


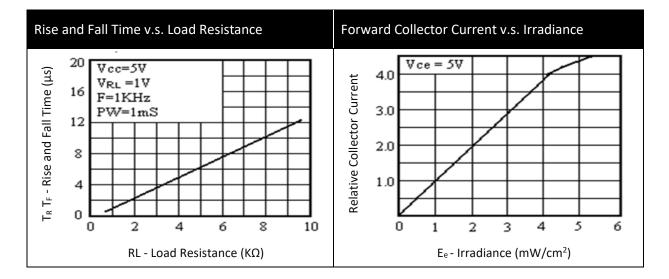


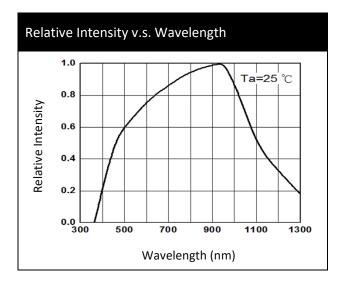
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ELECTRO-OPTICAL CHARACTERISTICS (PT):







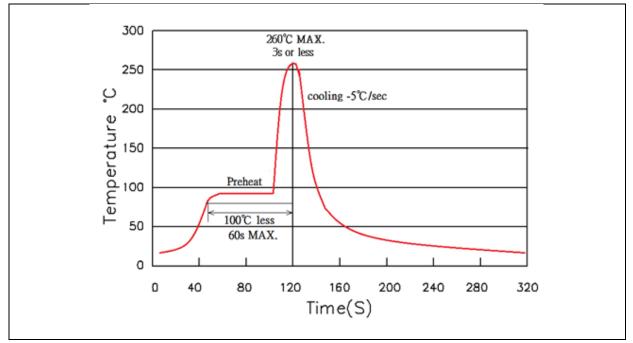


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

Solder Heat (DIP):



Note:

- 1. Recommend reflow temperature 245°C. The maximum soldering temperature should be limited to 260°C.
- 2. Maximum reflow soldering: 1 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

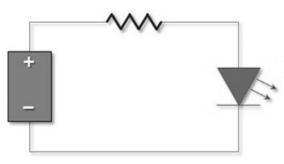
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 36hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	16/04/2023	Datasheet set-up.